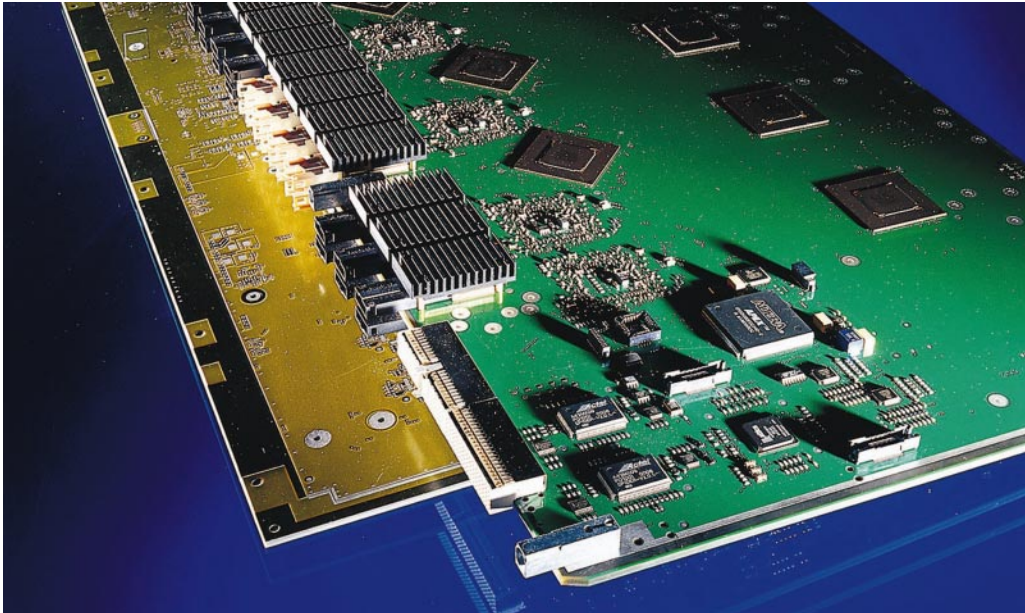


Finding High-tech PCB Competence

(High-density Interconnection) HDI Assembly Groups



*Produced with the add of new generation technologies:
The CX1000 and CCU High-speed Transfer Communications System from ALCATEL.
500 x 310 x 3 mm; 20 Layers FR4; 6 Microvia drill layers per side; Buried-vias; 1,2 Gbit/s*

A trend in the electronic industry has always been the reduction in size, and at the same time, an increase in performance.

The search for an answer to these constant demands has led to the introduction of the so-called HDI Assembly Group Technologies, or Printed Circuit Boards with the following specifications:

- > Extremely high connection density
(> 1000 connections/dm²)
- > Average contact density
(> 20 Pads/cm²)
- > Deployment of laser drilled Vias also called Microvias ($> \varnothing 80 \mu\text{m}$); technologically known as Sequential Build Up or SBU-PCBs
- > Up to a 3 Gbit/s transfer rate using the latest PCB materials



ALCATEL and TZCIS have since a number of years developed Printed Circuit Boards using this technology. Working closely together as partners, the design and production of the CCU originated. Support and intensive advice led to the production of the CX1000.

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